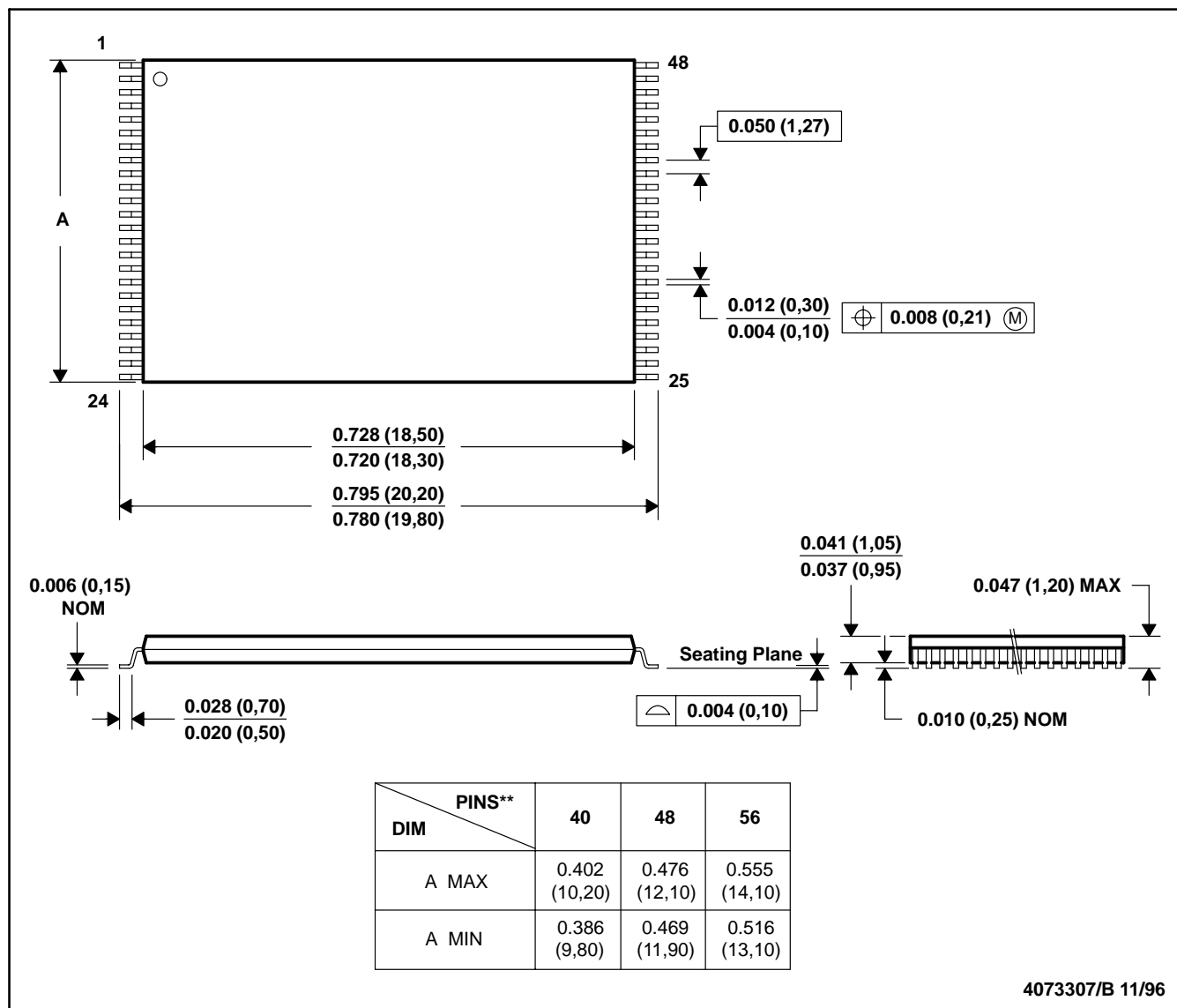


DCD (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

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